

## Specification Sheet

### CIGT252010LMR24MNE (2520 / EIA 1008)



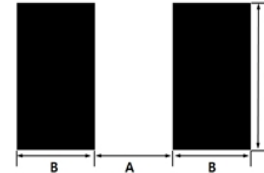
#### APPLICATION

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

#### FEATURES

Small power inductor for mobile devices  
Low DCR structure and high efficiency inductor for power circuits.  
Monolithic structure for high reliability  
Free of all RoHS-regulated substances  
Halogen free

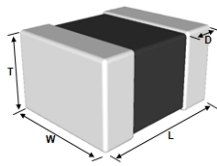
#### RECOMMENDED LAND PATTERN



Unit : mm

TYPE	2520
A	1.2
B	0.8
C	2.0

#### DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
2520	2.5±0.2	2.0±0.2	1.0 max	0.55±0.25

#### DESCRIPTION

Part no.	Size [inch/mm]	Thickness [mm] (max)	Inductance [uH]	Inductance tolerance (%)	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]	
					Max.	Typ.	Max.	Typ.	Max.	Typ.
CIGT252010LMR24MNE	1008/2520	1.0	0.24	±20	16	12	7.5	8.5	6	7

- \* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)
- \* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent
- \* Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or when current flows and temperature has risen to 40°C whichever is smaller. (Reference: ambient temperature is 25°C±10)
- (Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of the initial inductance value at 30% (Reference: ambient temperature is 25°C±10)
- (Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of the inductor is raised 40°C by DC current. (Reference: ambient temperature is 25°C±10)
- \* Absolute maximum voltage : Absolute maximum voltage DC 20V.
- \* Operating temperature range : -40 to +125°C (Including self-temperature rise)

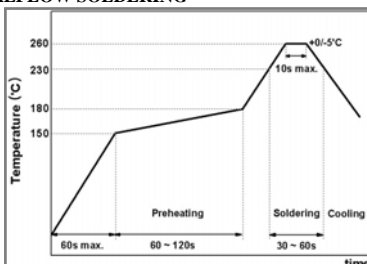
#### PRODUCT IDENTIFICATION

**CIG**    **T**    **2520**    **10**    **LM**    **R24**    **M**    **N**    **E**  
**(1)**    **(2)**    **(3)**    **(4)**    **(5)**    **(6)**    **(7)**    **(8)**    **(9)**

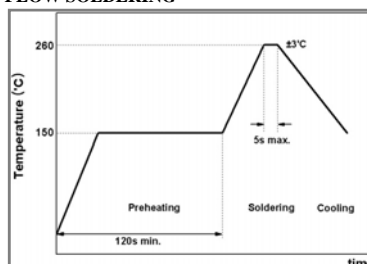
- (1) Power Inductor
- (2) Type (T: Metal Composite Thin Film Type)
- (3) Dimension (2520: 2.5mm x 2.0mm)
- (4) Thickness (10: 1.0mm)
- (5) Remark (Characterization Code)
- (6) Inductance (R24: 0.24 uH)
- (7) Tolerance (M:±20%)
- (8) Internal Code
- (9) Packaging (C:paper tape, E:embossed tape)

#### RECOMMENDED SOLDERING CONDITION

##### REFLOW SOLDERING



##### FLOW SOLDERING



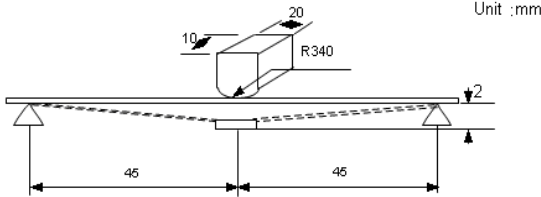
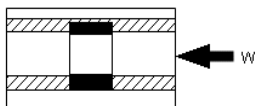
##### IRON SOLDERING

Temperature of Soldering Iron Tip	280°C max.
Preheating Temperature	150°C min.
Temperature Differential	ΔT≤130°C
Soldering Time	3sec max.
Wattage	50W max.

#### PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3000 pcs

## Reliability Test

Item	Specified Value	Test Condition
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 245±5℃ for 4±1 seconds.
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within ±20% to the initial.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 260±5℃ for 10 ±0.5 seconds.
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within ±20% to the initial.	Repeat 100 cycles under the following conditions. -40±3℃ for 30 min → 85±3℃ for 30 min
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.
Low Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at -55±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.
High Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at 125±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.
High Temperature Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.
Reflow Test	No mechanical damage Inductance change to be within ±20% to the initial	Peak 260±5℃, 3 times
Vibration Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5mm amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours).
Bending Test	No mechanical damage	Bending Limit; 2mm Test Speed; 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness : 1.6mm
		
Terminal Adhesion Test	No indication of peeling shall occur on the terminal electrode.	W(kgf)
		0.5
		TIME(sec)
		10±1
		
Drop Test	No mechanical damage Inductance change to be within ±20% to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops
Ipeak (AC+DC Load Life)	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, Load(Ipeak) for 120 hours. (Frequency:1MHz, Load(Ipeak):1.5hr on / 0.5hr off) Measure the test items after leaving at normal temperature and humidity for 24 hours. * Load(Ipeak) = Irms(max)×1.4